

TMUXHS221LV USB 2.0 480Mbps 2:1 or 1:2 Multiplexer or Demultiplexer Switch

1 Features

- Compatible to USB 2.0 and eUSB2 LS, FS, and HS physical layers
- Switch that supports differential signals up to 3Gbps
- Analog switch that can support most CMOS signals up to 3.3 V
- Data pins are 5 V tolerant
- Low RON of 3 Ω at $V_{I/O} = 0$ V
- High -3 dB BW of 3.3 GHz
- Excellent for USB 2.0 or eUSB2 HS signals at 240 MHz:
 - Insertion loss = -0.4 dB
 - Return loss = -22 dB
 - Off isolation or cross talk = -32 dB
- Minimal vertical and horizontal USB 2.0 HS eye attenuation
- 1.8 V supply voltage
- 1.2 or 1.8 V control logic inputs
- Extended industrial temperature range of -40 to 125°C
- Small 10-pin $1.8\text{ mm} \times 1.4\text{ mm}$, UQFN package
- Pin-to-pin and BOM-to-BOM with multiple sources

2 Applications

- PC and notebooks
- Gaming, TV, home theater, and entertainment
- Data center and enterprise computing
- Medical applications
- Test and measurements
- Factory automation and control
- Mobile phones and tablets

3 Description

The TMUXHS221LV is a high-speed bidirectional 2:1 or 1:2 multiplexer or demultiplexer optimized for USB 2.0 and eUSB2 LS, FS, and HS signaling. The TMUXHS221LV is an analog passive switch that works for many high-speed interfaces with data rates up to 3Gbps. The TMUXHS221LV supports either differential or single-ended CMOS signaling with a voltage range of -0.3 to 3.6 V.

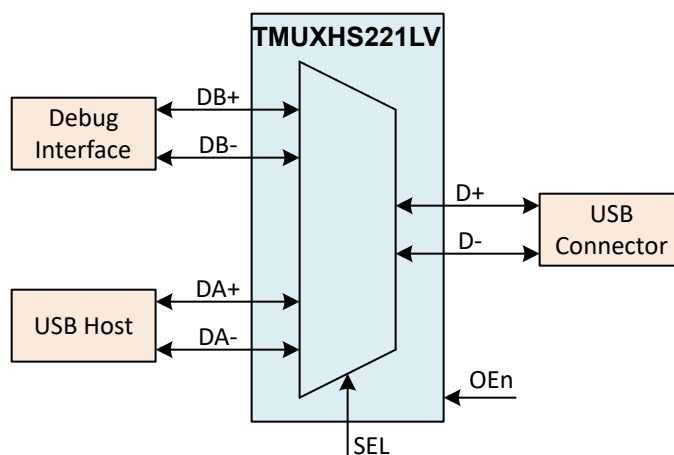
The ideal high-speed performance of the TMUXHS221LV results in minimal attenuation to the USB 2.0 or eUSB2 HS signal eye diagrams with very low channel ON resistance, high bandwidth, low reflection, and low added jitter. The device is optimized for ideal high frequency response so that passing USB 2.0 HS electrical compliance becomes easier. The data-paths of the device are also matched for best intra-pair skew performance.

The TMUXHS221LV has an extended temperature range that suits many rugged applications including industrial and high reliability use cases.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾
TMUXHS221LV	NKG (UQFN, 10)	$1.8\text{ mm} \times 1.4\text{ mm}$

- For all available packages, see the orderable addendum at the end of the data sheet.
- The package size (length $\times$ width) is a nominal value and includes pins, where applicable.



Application Use Case



Table of Contents

1 Features	1	7.2 Functional Block Diagram.....	9
2 Applications	1	7.3 Feature Description.....	9
3 Description	1	7.4 Device Functional Modes.....	9
4 Revision History	2	8 Application and Implementation	10
5 Pin Configuration and Functions	3	8.1 Application Information.....	10
6 Specifications	4	8.2 Typical Applications.....	10
6.1 Absolute Maximum Ratings.....	4	8.3 Power Supply Recommendations.....	14
6.2 ESD Ratings.....	4	8.4 Layout.....	14
6.3 Recommended Operating Conditions.....	4	9 Device and Documentation Support	15
6.4 Thermal Information.....	4	9.1 Related Documentation.....	15
6.5 Electrical Characteristics.....	5	9.2 Receiving Notification of Documentation Updates....	15
6.6 High-Speed Performance Parameters.....	5	9.3 Support Resources.....	15
6.7 Switching Characteristics.....	5	9.4 Trademarks.....	15
6.8 Typical Characteristics – S-Parameters.....	6	9.5 Electrostatic Discharge Caution.....	15
6.9 Typical Characteristics – R_{ON}	7	9.6 Glossary.....	15
6.10 Typical Characteristics – Eye Diagrams.....	8	10 Mechanical, Packaging, and Orderable Information	15
7 Detailed Description	9		
7.1 Overview.....	9		

4 Revision History

DATE	REVISION	NOTES
July 2023	*	Initial Release

5 Pin Configuration and Functions

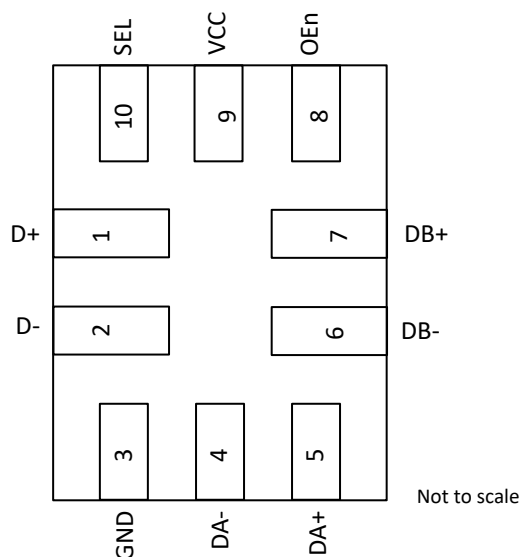


Figure 5-1. TMUXHS221LV NKG Package, 10-Pin UQFN (Top View)

Table 5-1. Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
D+	1	I/O	Data signals Common Port, positive
D-	2	I/O	Data signals Common Port, negative
DA+	5	I/O	Data signals Port A, positive
DA-	4	I/O	Data signals Port A, negative
DB+	7	I/O	Data signals Port B, positive
DB-	6	I/O	Data signals Port B, negative
SEL	10	IN	Switch control configuration signal as provided in Table 7-1 .
OEn	8	IN	
VCC	9	P	1.8 V power supply
GND	3	G	Ground

(1) IN = input, I/O = input or output, P = power, G = ground

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC-ABSMAX}	Supply voltage	−0.5	2.4	V
V _{I/O-ABSMAX}	Voltage	−0.5	5.5	V
V _{IN-ABSMAX}	Voltage	−0.5	4	V
I _{I/O-ABSMAX}	ON-state switch current		100	mA
T _{J-ABSMAX}	Junction temperature	−40	125	°C
T _{STG}	Storage temperature	−65	150	°C

- (1) Operation outside the *Absolute Maximum Rating* may cause permanent device damage. *Absolute Maximum Rating* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Condition*. If used outside the *Recommended Operating Condition* but within the *Absolute Maximum Rating*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.

6.2 ESD Ratings

		VALUE	UNIT
V _{ESD}	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±5000
		Charged device model (CDM), per ANSI/ESDA/JEDEC JS-002 ⁽²⁾	±1000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	TYP	MAX	UNIT
V _{CC}	Supply voltage	DC plus AC power should not exceed these limits	1.62	1.8	1.98	V
V _{CCRAMP}	Supply voltage ramp time		0.1		100	ms
V _{I/O}	Voltage range for data signals (V _{I/O})	D, DA, DB	−0.3		3.6	V
V _{IN}	Voltage range for control signals (V _{IN})	OEn, SEL	−0.3		3.6	V
T _J	Junction temperature				125	°C
T _A	Operating free-air/ambient temperature		−40		125	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TMUXHS221LV	UNIT
		NKG (UQFN)	
		10 PINS	
R _{θJA}	Junction-to-ambient thermal resistance - High K	225.9	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	93.5	°C/W
R _{θJB}	Junction-to-board thermal resistance	147.5	°C/W
ψ _{JT}	Junction-to-top characterization parameter	3.4	°C/W
ψ _{JB}	Junction-to-board characterization parameter	147.1	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.5 Electrical Characteristics

over operating free-air temperature and supply voltage range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I _{CC}	Device active current	OEn = L		10	17	μA
I _{STDN}	Device shutdown current	OEn = H		0.5	3	μA
C _{ON}	Output ON capacitance to GND	OEn = L		1.4		pF
R _{ON}	Channel ON resistance	V _{I/O} = 0 V, I _O = –8 mA		3	5.4	Ω
		V _{I/O} = 2.4 V, I _O = –8 mA		3.9	8	Ω
R _{ON,FLAT}	Channel ON resistance flatness defined as difference of R _{ON} over input voltage range	V _{I/O} = 0 V and V _{I/O} = 2.4 V; I _O = –8 mA		1		Ω
ΔR _{ON}	On-resistance match between pairs for the same channel at same V _{I/O} , VCC and T _A	V _{I/O} = 0 V; I _O = –8 mA		0.2		Ω
		V _{I/O} = 2.4 V; I _O = –8 mA		0.2		Ω
V _{IH}	Input high voltage, control pins (OEn, SEL)		0.9		3.6	V
V _{IL}	Input low voltage, control pins (OEn, SEL)		–0.3		0.25	
I _{IH,IN}	Input high current, control pins (OEn, SEL)	V _{IN} = 3.6 V			8	μA
I _{IL,IN}	Input low current, control pins (OEn, SEL)	V _{IN} = 0 V			0.2	μA
I _{I/O,H}	Input high current, data pins (Dx, DAx, DBx)	V _{I/O} = 3.6 V			5	μA
I _{I/O,L}	Input low current, data pins (Dx, DAx, DBx)	V _{I/O} = 0 V			0.2	μA
I _{HIZ,I/O}	Leakage current through turned off switch	OEn = H; V _{I/O} = 3.6 V			8	μA
I _{OFF,IN}	Failsafe leakage current for control pins (IN)	VCC = 0 V, V _{IN} = 1.98 V			12	μA
I _{OFF,I/O}	Failsafe leakage current for data pins (I/O)	VCC = 0 V, V _{I/O} = 3.6 V			12	μA

6.6 High-Speed Performance Parameters

PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
BW	–3-dB bandwidth	Relative to DC	3.3		GHz
I _L	Differential insertion loss	f = 10 MHz	–0.3		dB
		f = 240 MHz	–0.4		
R _L	Differential return loss	f = 10 MHz	–32		dB
		f = 240 MHz	–22		
O _{IRR}	Differential OFF isolation (D to DA/DB)	f = 10 MHz	–60		dB
		f = 240 MHz	–32		
XT	Single-Ended cross-talk (in between D+ and D- or DA+ and DA- or DB+ and DB-)	f = 10 MHz	–60		dB
		f = 240 MHz	–41		
XT _{diff}	Differential cross-talk (DA to DB or DB to DA)	f = 10 MHz	–64		dB
		f = 240 MHz	–32		

6.7 Switching Characteristics

over operating free-air temperature and supply voltage range (unless otherwise noted)

PARAMETER			MIN	TYP	MAX	UNIT
t _{PD}	Switch propagation delay			60	80	ps
t _{SW}	Switching time CTRL-to-Switch ON (SEL toggles in between H, L)	R _L = 50 Ω, C _L = 10 pF			1.5	μs
t _{OFF}	Time required for device ON-to-OFF transition (OEn = L to H)	R _L = 50 Ω, C _L = 10 pF			0.5	μs
t _{ON}	Time required for device OFF-to-ON transition (OEn = H to L)	R _L = 50 Ω, C _L = 10 pF			32	μs
t _{SK_INTRA}	Intra-pair output skew between positive and negative for same differential channel	For Dx to DAx or DBx channels		3	10	ps
t _{SK_INTER}	Inter-pair output skew between channels	For Dx to DAx or DBx channels		1	10	ps

6.8 Typical Characteristics – S-Parameters

Figure 6-1 and Figure 6-2 show differential insertion loss and return loss for a typical TMUXHS221LV channel, respectively. The excellent high-speed performance at 240 MHz results in minimal attenuation to the USB 2.0 or eUSB2 HS signal eye diagrams. Figure 6-3 shows differential crosstalk for a typical TMUXHS221LV channel. Note, the measurements provided are performed in TI evaluation board with board and equipment parasitics calibrated out.

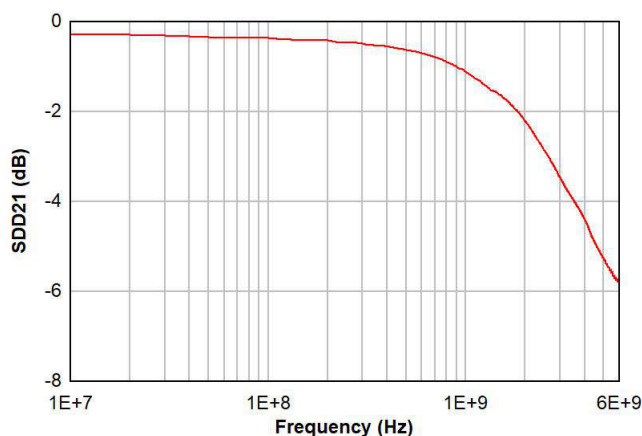


Figure 6-1. Typical Differential Insertion Loss vs Frequency

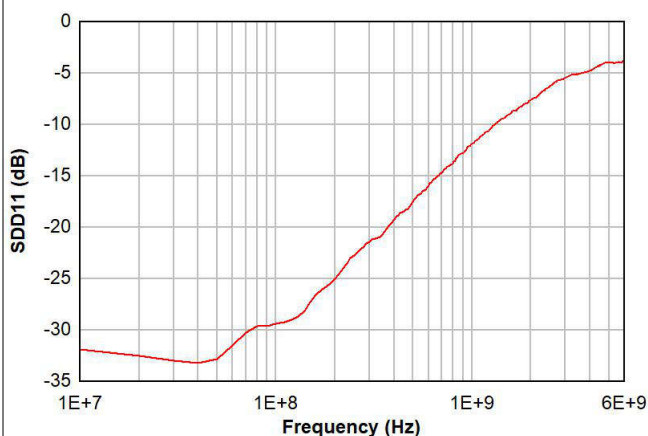


Figure 6-2. Typical Differential Return Loss vs Frequency

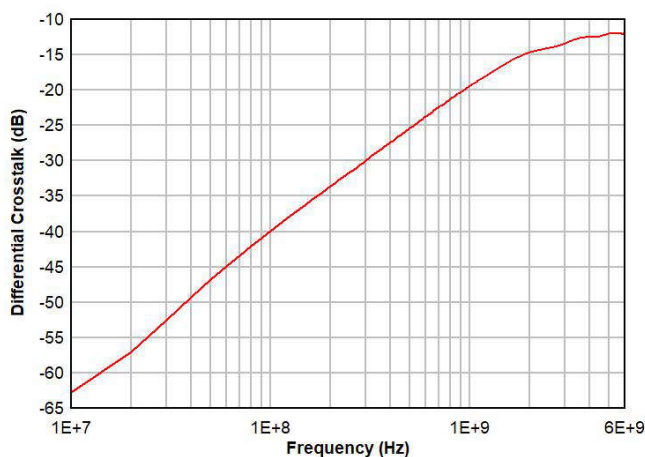


Figure 6-3. Typical Differential Crosstalk vs Frequency

6.9 Typical Characteristics – R_{ON}

Figure 6-4, Figure 6-5, and Figure 6-6 show switch ON resistance R_{ON} versus common mode voltage V_{CM} , supply voltage V_{CC} , and ambient temperature respectively. All curves are at nominal PVT conditions unless specified.

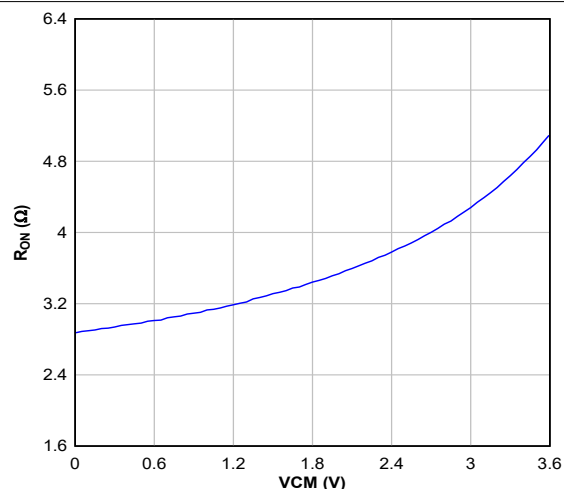


Figure 6-4. R_{ON} vs Common Mode Voltage V_{CM}

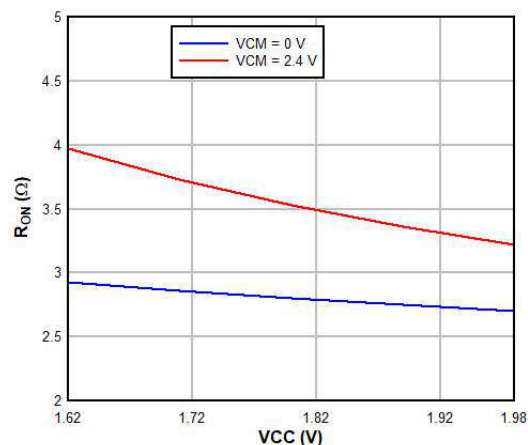


Figure 6-5. R_{ON} vs Supply Voltage V_{CC}

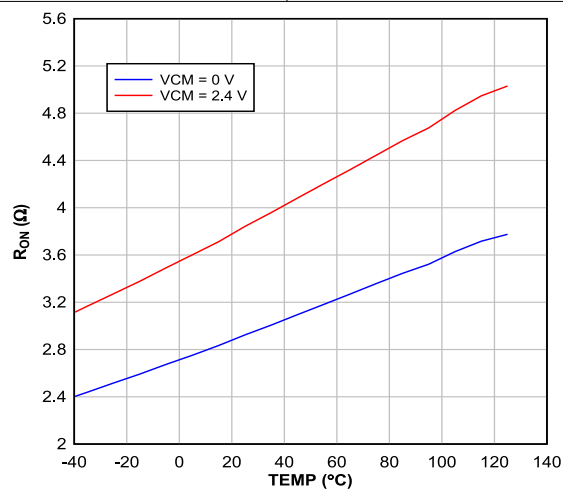


Figure 6-6. R_{ON} vs Ambient Temperature

6.10 Typical Characteristics – Eye Diagrams

Figure 6-7 and Figure 6-8 show a side-by-side comparison of 480Mbps USB 2.0 HS signals through calibration traces (without the device) and a typical TMUXHS221LV channel. The attenuation of the vertical and horizontal eye opening through the device is minimal. Also, the mux device adds a negligible amount of jitter to the signals.



Figure 6-7. Through Calibration Traces at 480Mbps



Figure 6-8. Through a Typical TMUXHS221LV Channel at 480Mbps

Figure 6-9 and Figure 6-10 show a side-by-side eye diagram comparison at 3Gbps signals through calibration traces (without the device) and a typical TMUXHS221LV channel. Attenuation of the vertical and horizontal eye opening through the device is minimal. The mux device adds only a small amount of jitter at 3Gbps.



Figure 6-9. Through Calibration Traces at 3Gbps



Figure 6-10. Through a Typical TMUXHS221LV Channel at 3Gbps

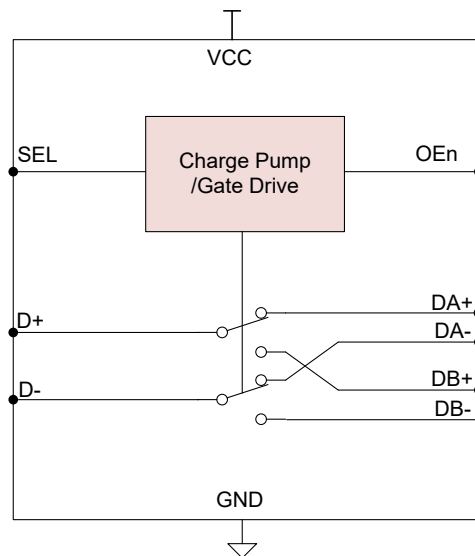
7 Detailed Description

7.1 Overview

The TMUXHS221LV is an analog passive mux with 2:1 or 1:2 multiplexer or demultiplexer that can work for any low-speed, high-speed, differential or single-ended signals. The signals must be within the allowable voltage range of -0.3 to 3.6 V. The device is optimized for eUSB2 and USB 2.0 LS, FS, and HS signaling.

The dynamic characteristics of the device allow high-speed switching with minimal attenuation to the signal eye diagram and little added jitter. While the device is recommended for the interfaces up to 3Gbps, actual data rates where the device can be used highly depends on the electrical channels. For low loss channels where adequate margin is maintained, the device can potentially be used for higher data rates.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Output Enable and Power Savings

The TMUXHS221LV has two power modes: active, or normal, operating mode and standby, or shutdown mode. During standby mode, the device consumes very little current to achieve ultra low power in systems where saving power is critical. To enter standby mode, OEn must be pulled high.

7.3.2 Data Line Biasing

The TMUXHS221LV does not contain any internal biasing. All channels of the device must be externally biased from either of the two sides to avoid floating channels.

7.4 Device Functional Modes

Table 7-1. Mux Configuration Control Logic for TMUXHS221LV⁽¹⁾

SEL	OEn	Mux Configuration
L	L	D to DA
H	L	D to DB
X	H	All channels are disabled and Hi-Z

- (1) The TMUXHS221LV can tolerate polarity inversions. Ensure that the polarity consistency is maintained for all signals. However the device cannot change polarity from input to output.

8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

The TMUXHS221LV is an analog high-speed mux/demux that can be used for routing differential as well as single ended CMOS signals through it. The device can be used for many high speed and low speed interfaces up to 3Gbps including the following:

- Universal Serial Bus (USB) 2.0 HS, FS, and LS
- Embedded Universal Serial Bus (eUSB) 2.0 HS, FS, and LS
- Inter-Integrated Circuit (I²C) Bus
- System Management Bus (SMBus™)
- Universal Asynchronous Receiver-Transmitter (UART™)
- Debug interface signals
- Mipi® Camera Serial Interface (CSI-2), Display Serial Interface (DSI)
- PCIe® clock
- DisplayPort™ Auxiliary and Hot Plug Detect Signals
- Universal Serial Bus Type C Sideband Use (USB-C™ SBU) signals
- Low Voltage Differential Signaling (LVDS)

An available GPIO pin of a controller or hard tie to voltage level H or L can easily control the mux or demux selection pin (SEL) of the device as an application requires.

Many interfaces require AC coupling the capacitors between the transmitter and receiver. The 0201 or 0402 capacitors are the preferred option, but other capacitors may be used depending on interface speed and signal integrity needs. If AC coupling capacitors are used on both sides of the TMUXHS221LV, then ensure the device is biased from either side, as there is no internal biasing to the device.

8.2 Typical Applications

8.2.1 Routing Debug Signals to USB Port

Many electronic end-equipment such as PCs, media players, point of sales registers, printers, cameras, headphones, smartphones, tablets, and so forth use USB ports (such as USB Type-A, USB Type-B, or USB Type-C™) for in-field or factory debug interface. In such use cases debug signals are routed to USB 2.0 pins of a USB port through a mux or demux device. TMUXHS221LV is a good fit for such use cases with its flexible data handling capability. TMUXHS221LV can handle virtually any debug interface signals as long as they are limited to -0.3 V (minimum) to 3.6 V (maximum). The device also provides very low attenuation to both USB 2.0 and debug signals with its very low channel ON resistance, high bandwidth, and low reflection.

Figure 8-1 shows a system implementation where USB 2.0 signals are multiplexed with debug interface signals into DP/DM wires of a USB port.

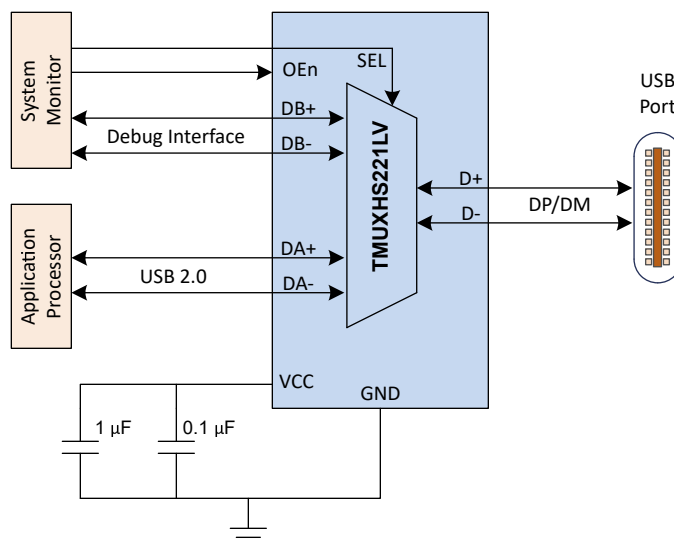


Figure 8-1. Routing Debug Signals to USB Port

8.2.1.1 Design Requirements

Table 8-1 provides various parameters and their expected values to implement the routing debug signals into the USB port. Note that the recommendation is for illustration purpose only.

Table 8-1. Design Parameters

DESIGN PARAMETER	VALUE
DA+, DA-, DB+, and DB-	Direct connect to processors, -0.3 – 3.6 V
SEL/OEn pin maximum voltage for low	0.4 V
SEL/OEn pin minimum voltage for high	1.4 V
Decoupling capacitor for VCC	0.1 µF and 1 µF

8.2.1.2 Detailed Design Procedure

Signal integrity is important because as a passive switch, the device provides no signal conditioning capability.

- Determine the loss profile between circuits that are to be muxed or demuxed.
- Provide clean impedance and electrical length matched board traces.
- Provide a control signal for the SEL and OEn pins.
- Provide good ground connection to the board ground plane.
- See the application schematics for the recommended decoupling capacitors from VCC pins to ground.

8.2.1.3 Application Curves

Figure 8-2 and Figure 8-3 show eye diagrams for USB 2.0 signals through calibration traces (without device) and TMUXHS221LV channel. A combination of very low channel ON resistance, high bandwidth, very low reflection (return loss), and low added jitter from the device allows 480Mbps USB 2.0 HS signals to remain unattenuated. Many system platforms struggle to pass USB 2.0 compliance due to high loss. TMUXHS221LV allows insertion of an analog mux device in the signal path without creating any additional signal integrity issues.

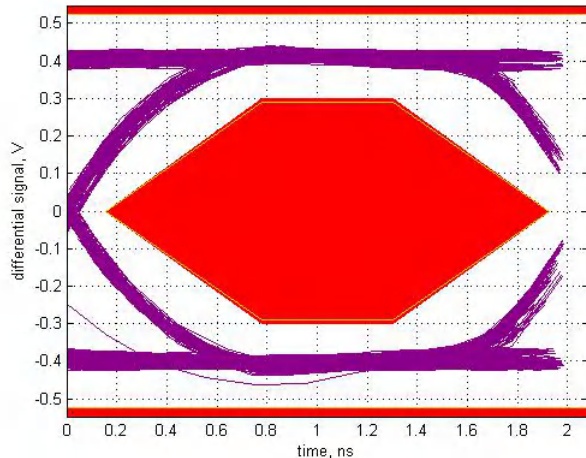


Figure 8-2. USB 2.0 HS Compliance Eye in TI Evaluation Board – Through Calibration Traces

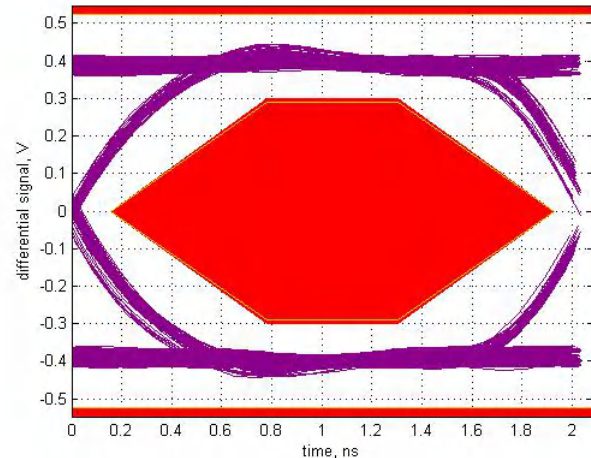


Figure 8-3. USB 2.0 HS Compliance Eye in TI Evaluation Board – Through TMUXHS221LV Channel

8.2.2 Systems Examples

8.2.2.1 PCIe Clock Muxing

Figure 8-4 shows an application where TMUXHS221LV is used to switch the PCIe clock. The device is measured in a TI evaluation board with an available clock source to show an added jitter less than 10 fs for all NOISE_FOLD and PCIe 5.0 CK filter versions, which is well below PCIe 5.0 clock specifications.

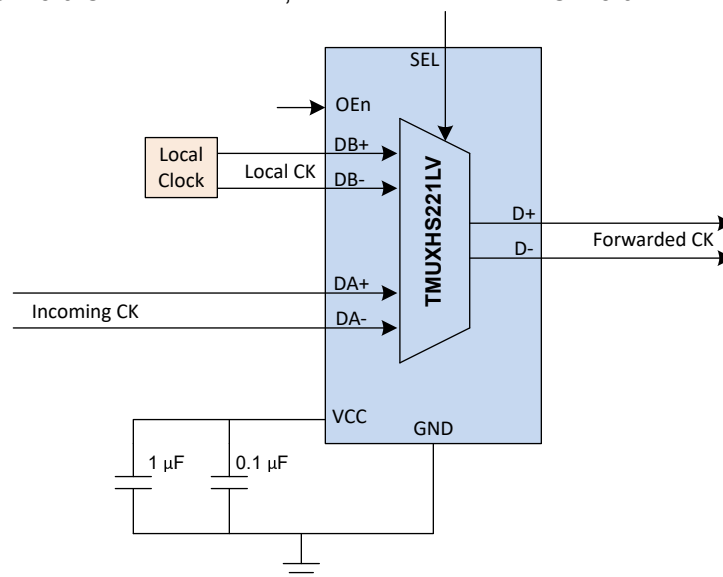


Figure 8-4. PCIe Clock Muxing

8.2.2.2 USB-C SBU Muxing

Figure 8-5 shows an application block diagram that implements SBU cross-muxing in a USB Type-C interface for implementing DisplayPort (DP) Alternate mode using the TMUXHS221LV. Note that the device has adequate bandwidth to support fast Auxiliary (AUX) signals. It is also capable of handling asymmetric biasing for DP AUX signals.

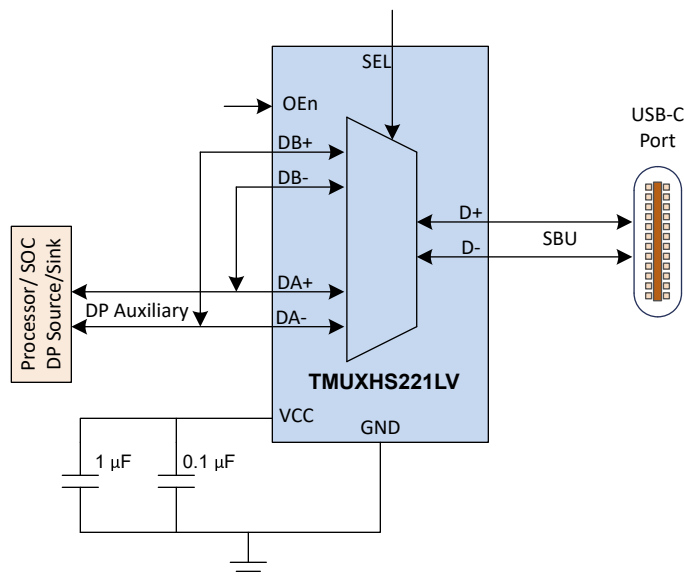


Figure 8-5. USB Type-C SBU Signals Muxing

8.2.2.3 Switching USB Port

Figure 8-6 shows an application block diagram where TMUXHS221LV is used to switch the USB port in between a hand-held portable device and its connected dock.

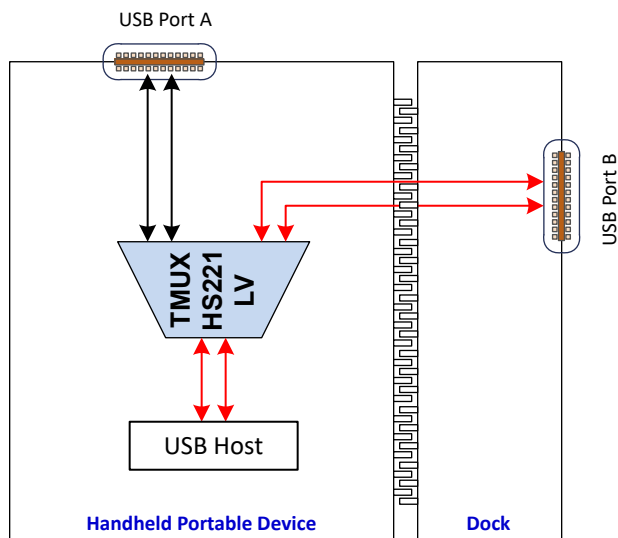


Figure 8-6. Switching USB Port

8.3 Power Supply Recommendations

The TMUXHS221LV does not require a power supply sequence. However, TI recommends to enable the device after VCC is stable and within specification. TI also recommends to place ample decoupling capacitors at the device VCC near the pin.

8.4 Layout

8.4.1 Layout Guidelines

A high-speed USB connection is made through a shielded, twisted pair cable with a differential characteristic impedance. In the layout, the impedance of D+ and D– traces should match the cable characteristic differential impedance for optimal performance. The high-speed D+/D– traces should always be matched and must be no more than 4 inches, otherwise the eye diagram performance may be degraded.

- Place supply bypass capacitors as close to the VCC pin as possible.
- Avoid placing the bypass capacitors near the D+/D–traces.
- Route the high-speed USB signals using a minimum of vias and corners which will reduce signal reflections and impedance changes. Each via introduces discontinuities in the signal's transmission line and increases the chance of picking up interference from the other layers of the board. When a via must be used, increase the clearance size around it to minimize its capacitance.
- Be careful when designing test points on twisted pair lines; through-hole pins are not recommended.
- When it becomes necessary to turn 90°, use two 45° turns or an arc instead of making a single 90° turn. This reduces reflections on the signal traces by minimizing impedance discontinuities.
- Do not route USB traces under or near crystals, oscillators, clock signal generators, switching regulators, mounting holes, magnetic devices, or ICs that use or duplicate clock signals.
- Avoid stubs on the high-speed USB signals because they cause signal reflections. If a stub is unavoidable, then the stub should be less than 200 mm.
- Route all high-speed USB signal traces over continuous planes (VCC or GND) with no interruptions.
- Avoid crossing over anti-etch, commonly found with plane split.

For high speed layout guidelines, refer to [High-Speed Layout Guidelines for Signal Conditioners and USB Hubs application note](#).

8.4.2 Layout Example

Figure 8-7 shows a TMUXHS221LV layout example.

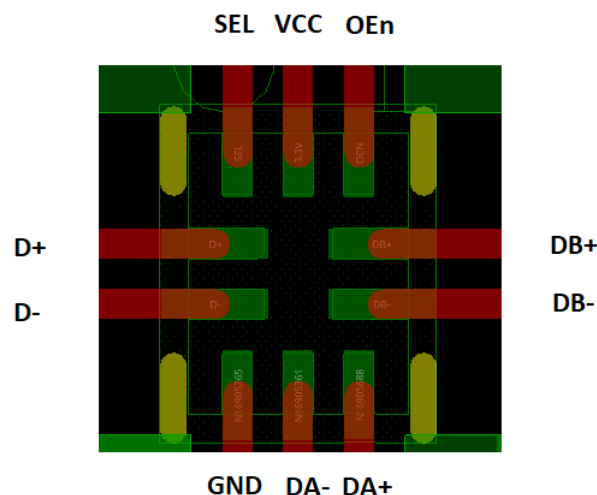


Figure 8-7. TMUXHS221LV Layout Example

9 Device and Documentation Support

9.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [High-Speed Layout Guidelines for Signal Conditioners and USB Hubs application note](#)

9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](#). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

9.4 Trademarks

SMBus™ is a trademark of Intel.

UART™ is a trademark of Synopsys, Inc.

DisplayPort™ is a trademark of VESA.

USB-C™ and USB Type-C™ are trademarks of USB Implementers Forum.

TI E2E™ is a trademark of Texas Instruments.

Mipi® is a registered trademark of MIPI Alliance, Inc.

PCIe® is a registered trademark of PCI-SIG.

All trademarks are the property of their respective owners.

9.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMUXHS221LVNKGR	Active	Production	UQFN (NKG) 10	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	21L
TMUXHS221LVNKGR.A	Active	Production	UQFN (NKG) 10	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	21L
TMUXHS221LVNKG	Active	Production	UQFN (NKG) 10	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	21L
TMUXHS221LVNKG.T.A	Active	Production	UQFN (NKG) 10	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	21L

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

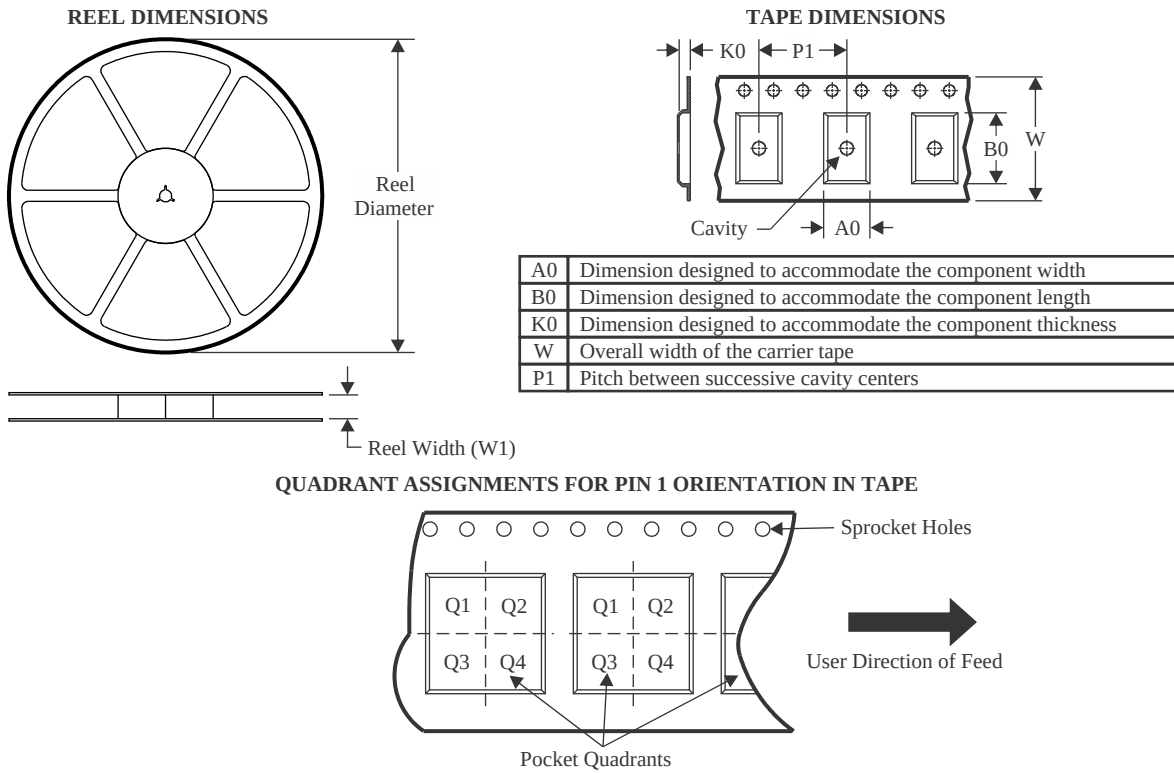
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

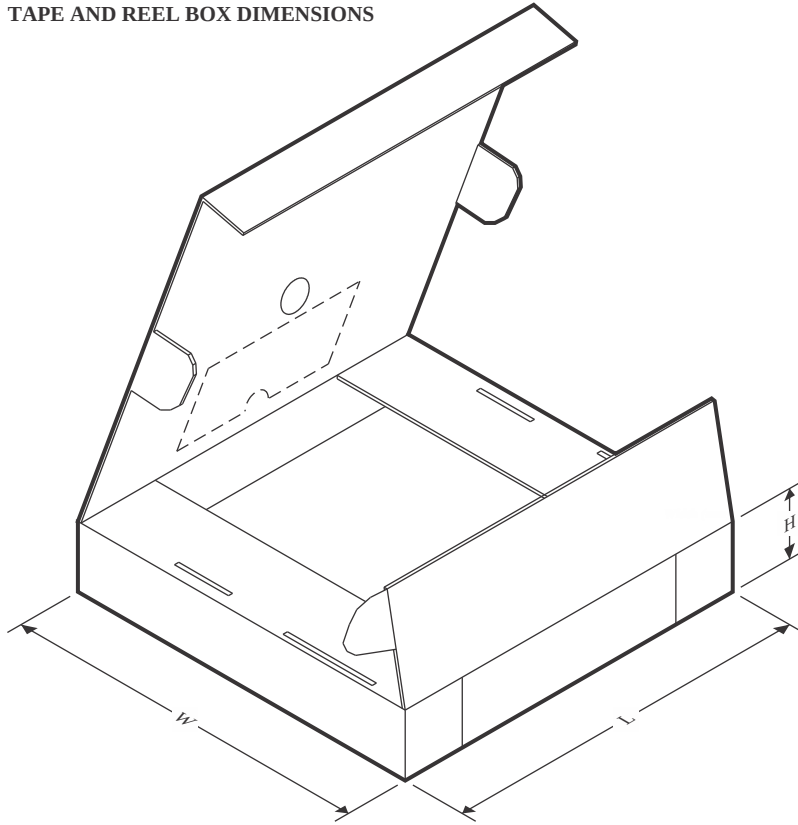
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TMUXHS221LVNKGR	UQFN	NKG	10	3000	180.0	8.4	1.6	2.0	0.7	4.0	8.0	Q1
TMUXHS221LVNKGT	UQFN	NKG	10	250	180.0	8.4	1.6	2.0	0.7	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



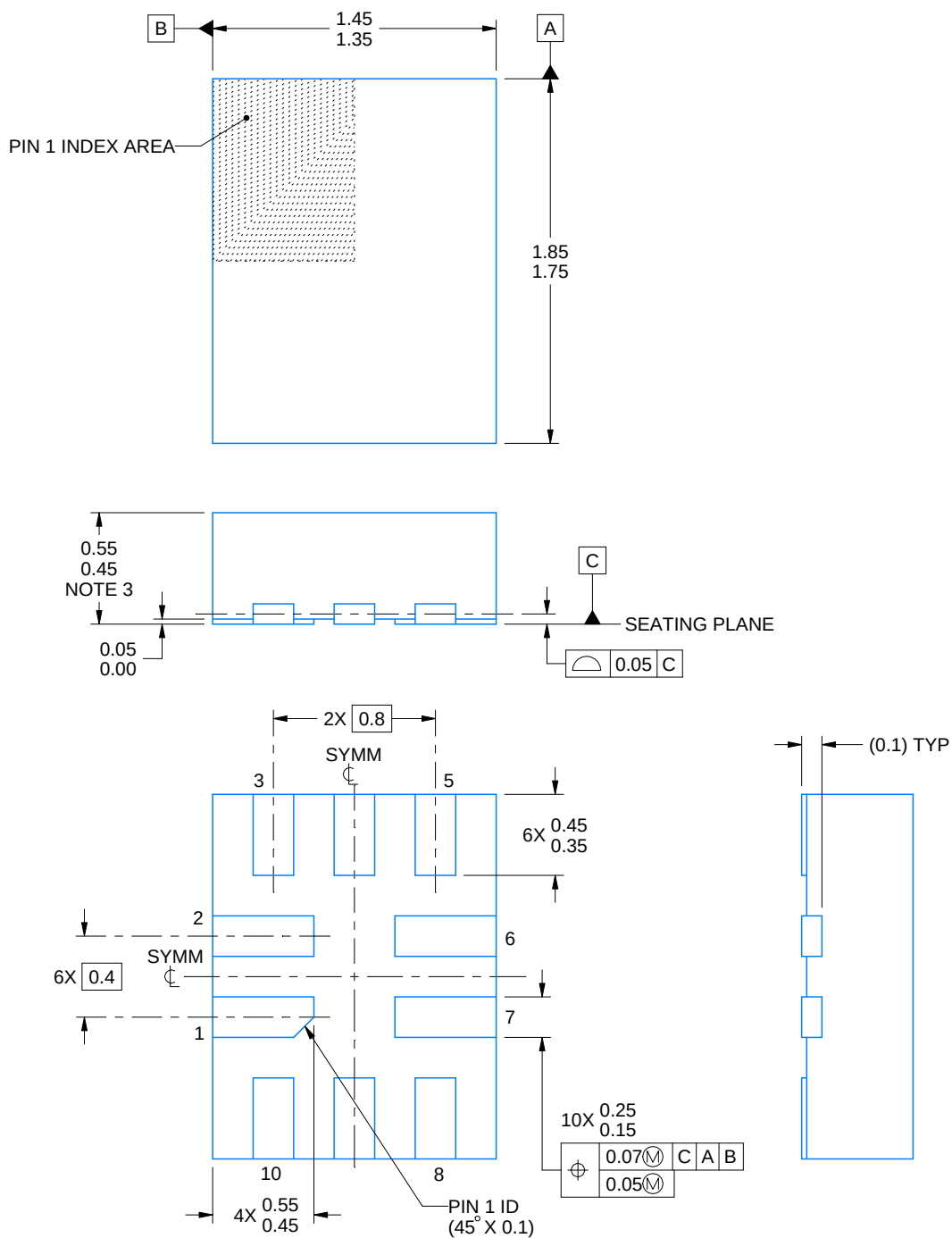
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TMUXHS221LVNKGR	UQFN	NKG	10	3000	210.0	185.0	35.0
TMUXHS221LVNKGT	UQFN	NKG	10	250	210.0	185.0	35.0



UQFN - 0.55 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



4228479/A 02/2022

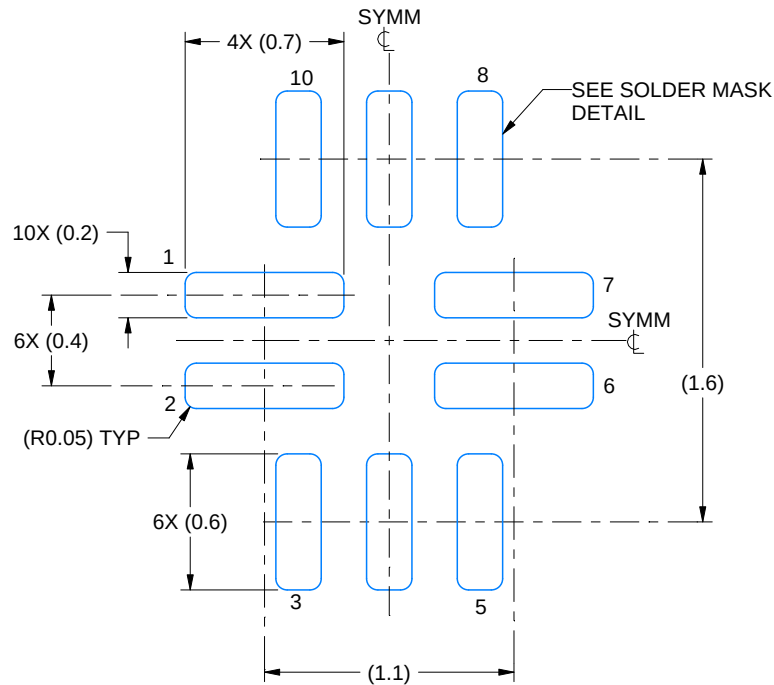
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package complies to JEDEC MO-288 variation UDEE, except minimum package height.

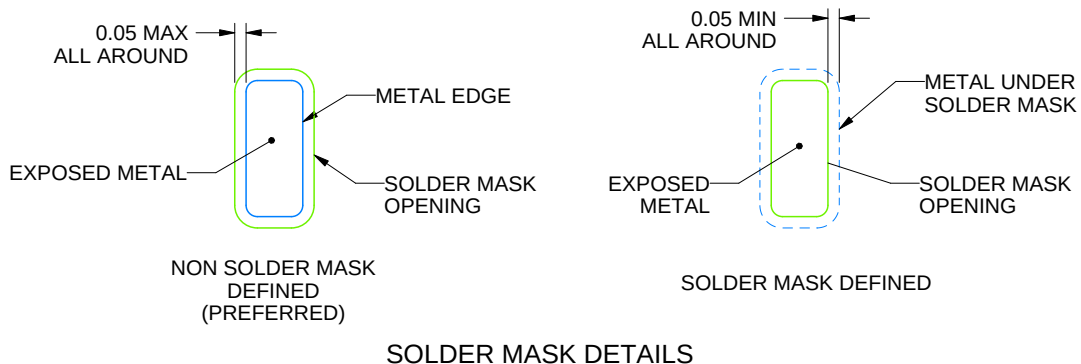
NKG0010A

UQFN - 0.55 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 30X



4228479/A 02/2022

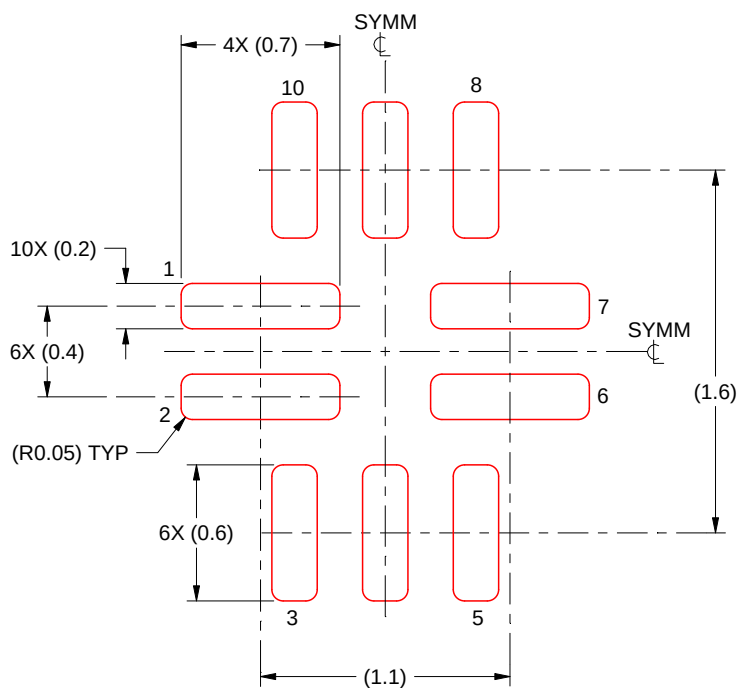
NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slue271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

NKG0010A

UQFN - 0.55 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.1 MM THICK STENCIL
SCALE: 30X

4228479/A 02/2022

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2025, Texas Instruments Incorporated